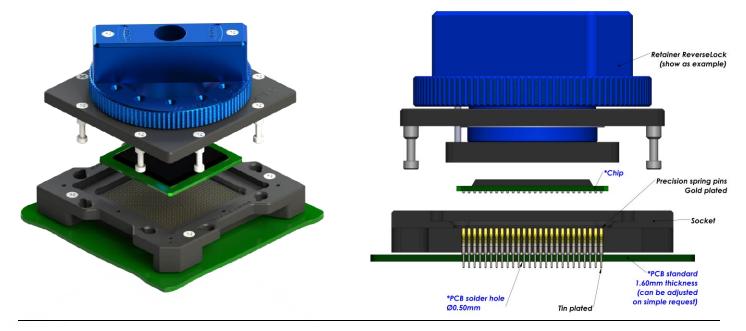
For BGA / Bumped chip / WLCSP / eMMC Package **1.00 mm pitch** (from 1.00 mm up to 1.26 mm)





## *E-tec Interconnect AG is the world leading Test socket manufacturer*

The Through-hole socket uses the same footprint as your chip. Socket is simply placed and wave soldered onto the PCB in the same way as the chip and it only requires a small amount of additional board space. Through-hole sockets are available with all retention systems. Please note, we will always request the chip data to ensure we offer a compatible socket.

Specifications contact type code 1070									
Application	Through-hole technology	Force	25 gr						
Mounting	THT	Current rating	1.8 A						
Bandwidth (GHz@-1dB)	3.4 GHz	Capacitance pF	1.03 pF						
Contact resistance	<100mOhm	Inductance nH	1.80 nH						
Chip contact tip shape	Single Point tip or Concave tip	Temperature range	-55°C to +150°C						
PCB tip shape	Through-hole	Mating cycles	100 K						

How to order

## **BU # #### -107# - ###### #5 #**

Shape of tip U : Concave	<u>Nbr of</u> <u>contacts</u>	Contact type 70 : Standard THT 72 : Special THT to plug into MGS adapters			Plating 95:Tin / Gold		p <b>tion code</b> (see page 16-19) Dead bug
Options: P : Pointed	Depends on ballcount of chip				55:Gold / Go		Multi frames Multi packages
S : Spring C : Crown					Other on reque	L :	Custom opening slot Locating pegs
Retention frame type (Lid) (see page 12-15)				<u>Grid code /</u> Config. code		H	Alignment plate Heatsink
W: TwistLock F : FastLock		S: ScrewLock Q: Open QuickLock	<200 contacts)	Will be given by the factory after receipt of the chip datashee		P	Fan + Heatsink Thermal drain pad
B : SpringLock H : Open Clamshell Alu (<200 contacts)		D: QuickLock (>200 c M: Injection Molded (				1 :	Transparent lid Steel retention lid
J : Clamshell Alu (>200 contacts) L : Open Lever Clamshell Alu (>200 contacts)		R: ReverseLock T: SlimLock				Т	Aluminium retention lid
						G	Handling button

